



# STP3NB90 STP3NB90FP

N-CHANNEL 900V - 4  $\Omega$  - 3.5 A TO-220/TO-220FP

PowerMesh™ MOSFET

| TYPE       | V <sub>DSS</sub> | R <sub>DS(on)</sub> | I <sub>D</sub> | P <sub>w</sub> |
|------------|------------------|---------------------|----------------|----------------|
| STP3NB90   | 900 V            | < 4.2 $\Omega$      | 3.5 A          | 110 W          |
| STP3NB90FP | 900 V            | < 4.2 $\Omega$      | 3.5 A          | 35 W           |

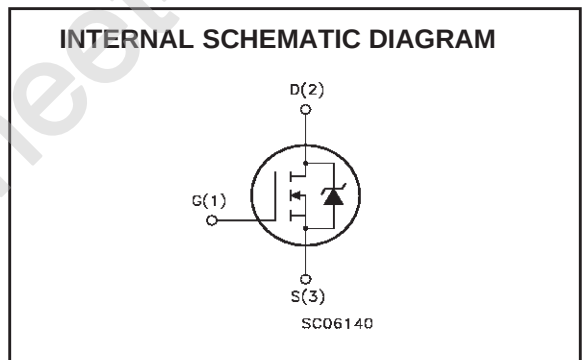
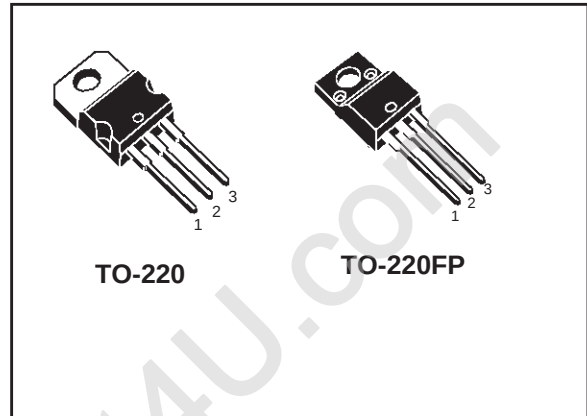
- TYPICAL R<sub>DS(on)</sub> = 4  $\Omega$
- EXTREMELY HIGH dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- GATE CHARGE MINIMIZED
- VERY LOW INTRINSIC CAPACITANCES

## DESCRIPTION

Using the latest high voltage MESH OVERLAY™ process, STMicroelectronics has designed an advanced family of power MOSFETs with outstanding performances. The new patent pending strip layout coupled with the Company's proprietary edge termination structure, gives the lowest R<sub>DS(on)</sub> per area, exceptional avalanche and dv/dt capabilities and unrivalled gate charge and switching characteristics.

## APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES AND MOTOR DRIVE



## ORDERING INFORMATION

| SALES TYPE | MARKING  | PACKAGE  | PACKAGING |
|------------|----------|----------|-----------|
| STP3NB90   | P3NB90   | TO-220   | TUBE      |
| STP3NB90FP | P3NB90FP | TO-220FP | TUBE      |

## STP3NB90 - STP3NB90FP

### ABSOLUTE MAXIMUM RATINGS

| Symbol             | Parameter                                               | Value      |            | Unit                |
|--------------------|---------------------------------------------------------|------------|------------|---------------------|
|                    |                                                         | STP3NB90   | STP3NB90FP |                     |
| $V_{DS}$           | Drain-source Voltage ( $V_{GS} = 0$ )                   | 900        |            | V                   |
| $V_{DGR}$          | Drain-gate Voltage ( $R_{GS} = 20\text{ k}\Omega$ )     | 900        |            | V                   |
| $V_{GS}$           | Gate- source Voltage                                    | $\pm 30$   |            | V                   |
| $I_D$              | Drain Current (continuous) at $T_C = 25^\circ\text{C}$  | 3.5        | 3.5 (*)    | A                   |
| $I_D$              | Drain Current (continuous) at $T_C = 100^\circ\text{C}$ | 2.2        | 1.26 (*)   | A                   |
| $I_{DM}^{(*)}$     | Drain Current (pulsed)                                  | 14         | 14 (*)     | A                   |
| $P_{TOT}$          | Total Dissipation at $T_C = 25^\circ\text{C}$           | 110        | 30         | W                   |
|                    | Derating Factor                                         | 0.87       | 0.24       | W/ $^\circ\text{C}$ |
| $dv/dt$ (1)        | Peak Diode Recovery voltage slope                       | 4.5        |            | V/ns                |
| $V_{ISO}$          | Insulation Withstand Voltage (DC)                       | -          | 2000       | V                   |
| $T_j$<br>$T_{stg}$ | Operating Junction Temperature<br>Storage Temperature   | -55 to 150 |            | $^\circ\text{C}$    |

(\*)Pulse width limited by safe operating area

(1)  $I_{SD} \leq 3.5\text{A}$ ,  $di/dt \leq 200\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_j \leq T_{jMAX}$

(\*)Limited only by maximum temperature allowed

### THERMAL DATA

|                   |                                                                                           | TO-220      | TO-220FP |                                               |
|-------------------|-------------------------------------------------------------------------------------------|-------------|----------|-----------------------------------------------|
| Rthj-case         | Thermal Resistance Junction-case Max                                                      | 1.14        | 4.2      | $^\circ\text{C}/\text{W}$                     |
| Rthj-amb<br>$T_I$ | Thermal Resistance Junction-ambient Max<br>Maximum Lead Temperature For Soldering Purpose | 62.5<br>300 |          | $^\circ\text{C}/\text{W}$<br>$^\circ\text{C}$ |

### AVALANCHE CHARACTERISTICS

| Symbol   | Parameter                                                                                                       | Max Value | Unit |
|----------|-----------------------------------------------------------------------------------------------------------------|-----------|------|
| $I_{AR}$ | Avalanche Current, Repetitive or Not-Repetitive<br>(pulse width limited by $T_j$ max)                           | 3.5       | A    |
| $E_{AS}$ | Single Pulse Avalanche Energy<br>(starting $T_j = 25^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ ) | 230       | mJ   |

**ELECTRICAL CHARACTERISTICS** ( $T_{CASE} = 25\text{ }^{\circ}\text{C}$  UNLESS OTHERWISE SPECIFIED)  
ON/OFF

| Symbol        | Parameter                                        | Test Condition s                                                                                   | Min. | Typ. | Max.      | Unit                           |
|---------------|--------------------------------------------------|----------------------------------------------------------------------------------------------------|------|------|-----------|--------------------------------|
| $V_{(BR)DSS}$ | Drain-source Breakdown Voltage                   | $I_D = 1\text{ mA}$ , $V_{GS} = 0$                                                                 | 900  |      |           | V                              |
| $I_{DSS}$     | Zero Gate Voltage Drain Current ( $V_{GS} = 0$ ) | $V_{DS} = \text{Max Rating}$<br>$V_{DS} = \text{Max Rating}$ , $T_C = 125\text{ }^{\circ}\text{C}$ |      |      | 1<br>50   | $\mu\text{A}$<br>$\mu\text{A}$ |
| $I_{GSS}$     | Gate-body Leakage Current ( $V_{DS} = 0$ )       | $V_{GS} = \pm 30\text{ V}$                                                                         |      |      | $\pm 100$ | nA                             |
| $V_{GS(th)}$  | Gate Threshold Voltage                           | $V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$                                                 | 3    | 4    | 5         | V                              |
| $R_{DS(on)}$  | Static Drain-source On Resistance                | $V_{GS} = 10\text{ V}$ , $I_D = 1.7\text{ A}$                                                      |      | 4    | 4.2       | $\Omega$                       |

**DYNAMIC**

| Symbol                              | Parameter                                                               | Test Condition s                                           | Min. | Typ.             | Max. | Unit           |
|-------------------------------------|-------------------------------------------------------------------------|------------------------------------------------------------|------|------------------|------|----------------|
| $g_{fs(1)}$                         | Forward Transconductance                                                | $V_{DS} = 15\text{ V}$ ; $I_D = 1.7\text{ A}$              |      | 3                |      | S              |
| $C_{iss}$<br>$C_{oss}$<br>$C_{rss}$ | Input Capacitance<br>Output Capacitance<br>Reverse Transfer Capacitance | $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0$ |      | 690<br>82<br>8.5 |      | pF<br>pF<br>pF |

**SWITCHING ON**

| Symbol                        | Parameter                                                    | Test Condition s                                                                                                                 | Min. | Typ.             | Max. | Unit           |
|-------------------------------|--------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------|------|------------------|------|----------------|
| $t_{d(on)}$<br>$t_r$          | Turn-on Delay Time<br>Rise Time                              | $V_{DD} = 450\text{ V}$ , $I_D = 1.75\text{ A}$<br>$R_G = 4.7\Omega$ , $V_{GS} = 10\text{ V}$<br>(Resistive Load see , Figure 3) |      | 17<br>12         |      | ns<br>ns       |
| $Q_g$<br>$Q_{gs}$<br>$Q_{gd}$ | Total Gate Charge<br>Gate-Source Charge<br>Gate-Drain Charge | $V_{DD} = 720\text{ V}$ , $I_D = 3.5\text{ A}$ ,<br>$V_{GS} = 10\text{ V}$                                                       |      | 22<br>7.3<br>9.2 |      | nC<br>nC<br>nC |

**SWITCHING OFF**

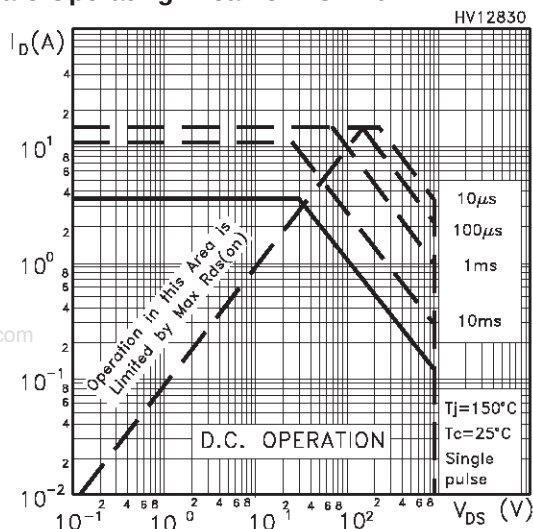
| Symbol                          | Parameter                                             | Test Conditions                                                                                                                   | Min. | Typ.           | Max. | Unit           |
|---------------------------------|-------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------|------|----------------|------|----------------|
| $t_{d(off)}$<br>$t_f$           | Turn-off Delay Time<br>Fall Time                      | $V_{DD} = 450\text{ V}$ , $I_D = 1.75\text{ A}$<br>$R_G = 4.7\Omega$ , $V_{GS} = 10\text{ V}$<br>(Resistive Load see , Figure 3)  |      | 26<br>39       |      | ns<br>ns       |
| $t_{r(Voff)}$<br>$t_f$<br>$t_c$ | Off-voltage Rise Time<br>Fall Time<br>Cross-over Time | $V_{DD} = 720\text{ V}$ , $I_D = 3.5\text{ A}$ ,<br>$R_G = 4.7\Omega$ , $V_{GS} = 10\text{ V}$<br>(Inductive Load see , Figure 5) |      | 16<br>20<br>25 |      | ns<br>ns<br>ns |

**SOURCE DRAIN DIODE**

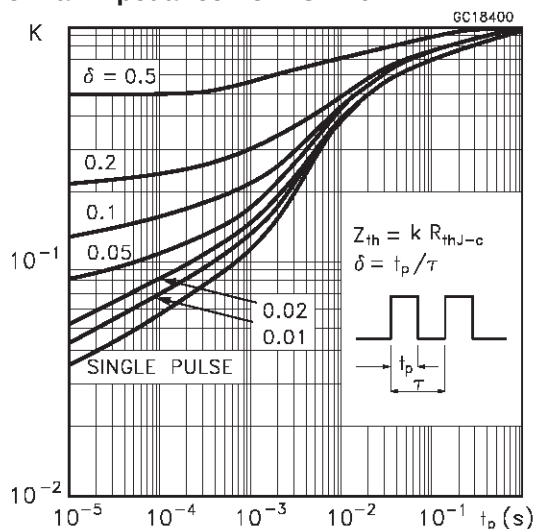
| Symbol                            | Parameter                                                                    | Test Condition s                                                                                                                                        | Min. | Typ.             | Max.      | Unit                     |
|-----------------------------------|------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------|------|------------------|-----------|--------------------------|
| $I_{SD}$<br>$I_{SDM(2)}$          | Source-drain Current<br>Source-drain Current (pulsed)                        |                                                                                                                                                         |      |                  | 3.5<br>14 | A<br>A                   |
| $V_{SD(1)}$                       | Forward On Voltage                                                           | $I_{SD} = 3.5\text{ A}$ , $V_{GS} = 0$                                                                                                                  |      |                  | 1.6       | V                        |
| $t_{rr}$<br>$Q_{rr}$<br>$I_{RRM}$ | Reverse Recovery Time<br>Reverse Recovery Charge<br>Reverse Recovery Current | $I_{SD} = 3.5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,<br>$V_{DD} = 100\text{ V}$ , $T_j = 150^{\circ}\text{C}$<br>(see test circuit, Figure 5) |      | 630<br>3.5<br>11 |           | ns<br>$\mu\text{C}$<br>A |

Note: 1. Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %.  
2. Pulse width limited by safe operating area.

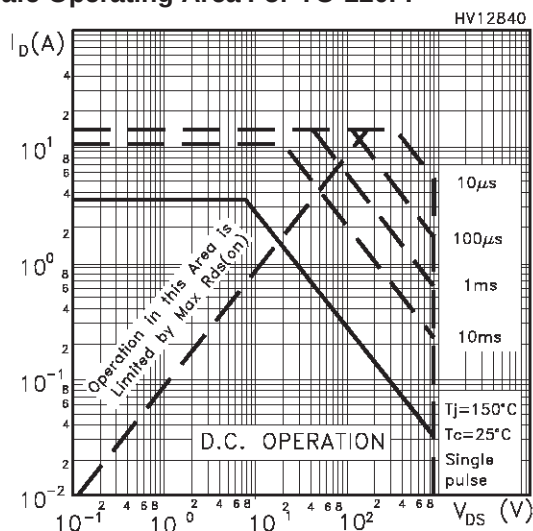
### Safe Operating Area For TO-220



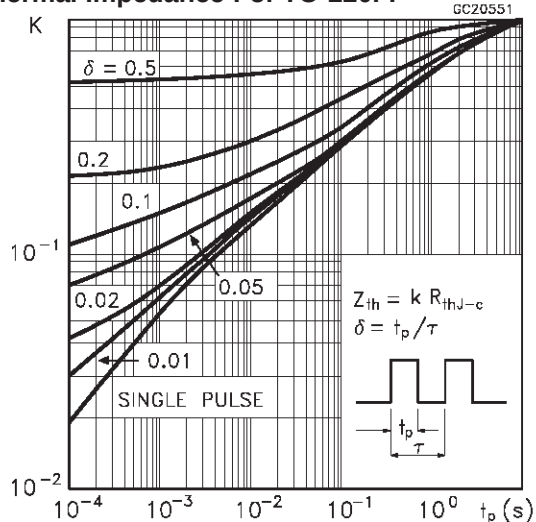
### Thermal Impedance For TO-220



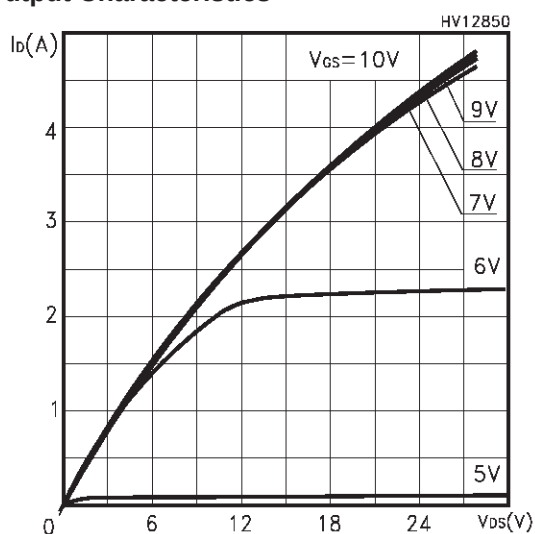
### Safe Operating Area For TO-220FP



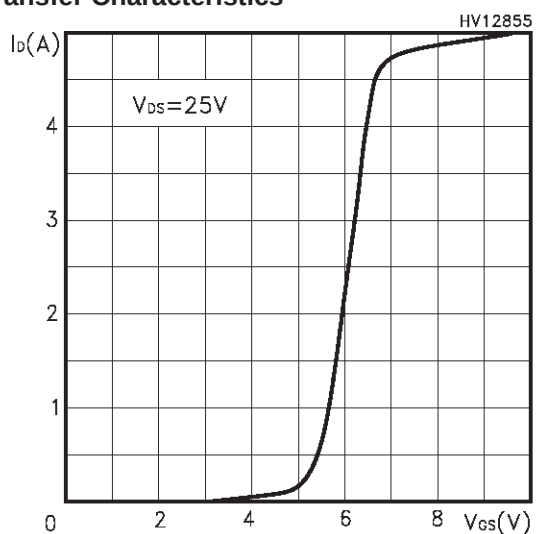
### Thermal Impedance For TO-220FP



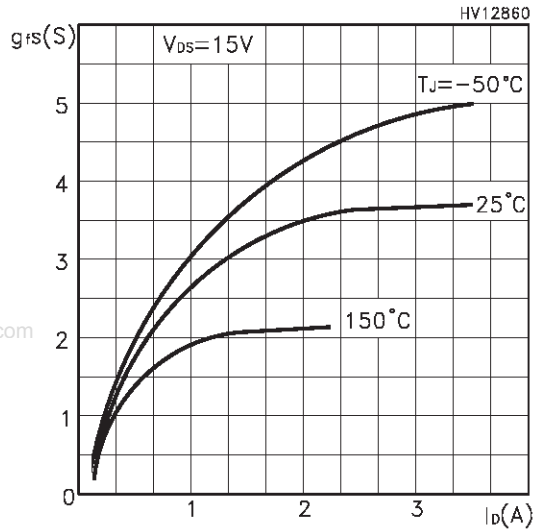
### Output Characteristics



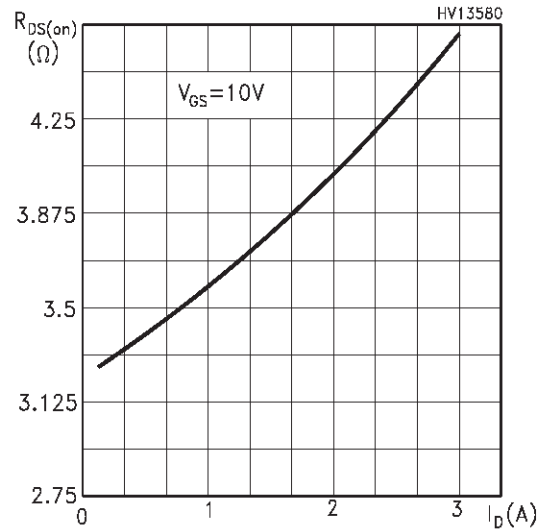
### Transfer Characteristics



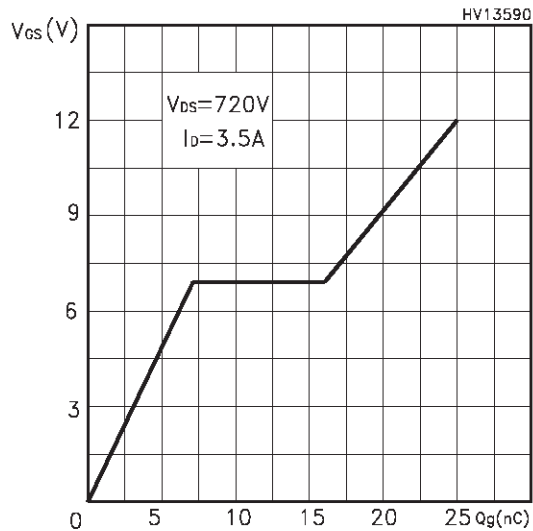
### Transconductance



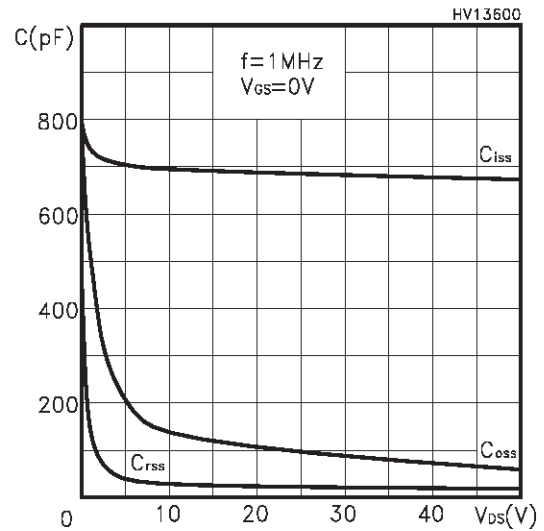
### Static Drain-source On Resistance



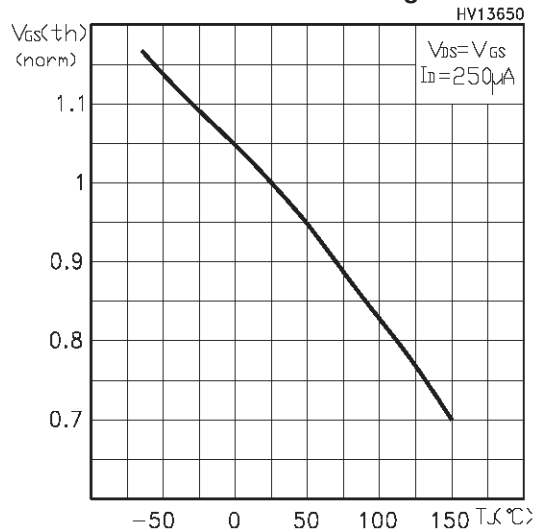
### Gate Charge vs Gate-source Voltage



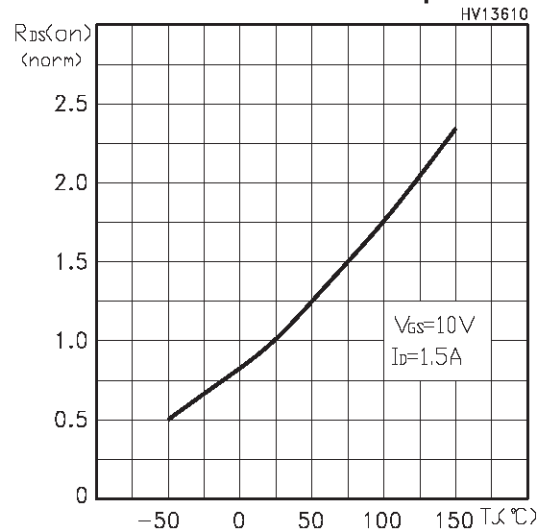
### Capacitance Variations



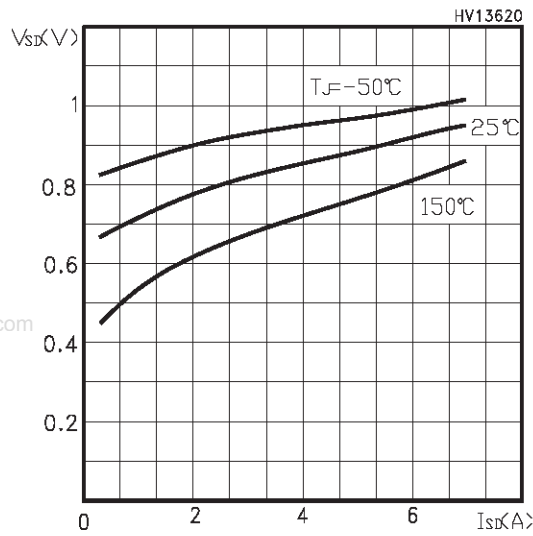
### Normalized Gate Threshold Voltage vs Temp.



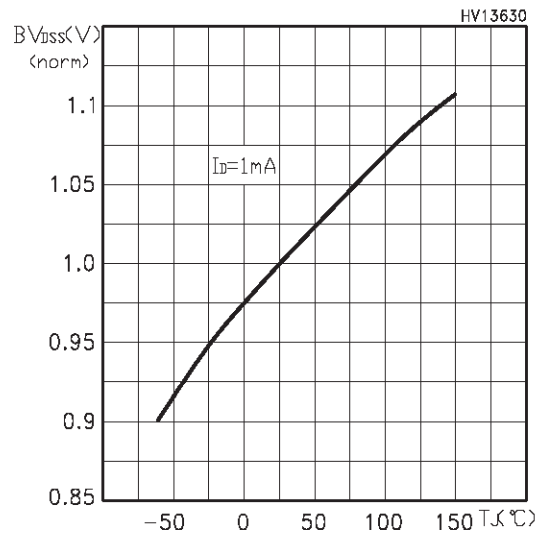
### Normalized On Resistance vs Temperature



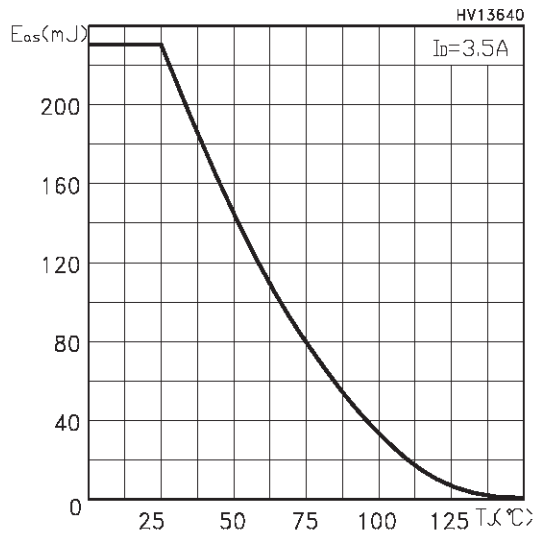
Source-drain Diode Forward Characteristics



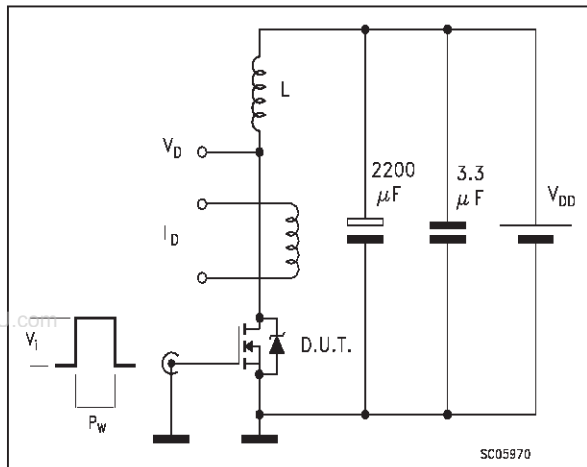
Normalized BVDSS vs Temperature



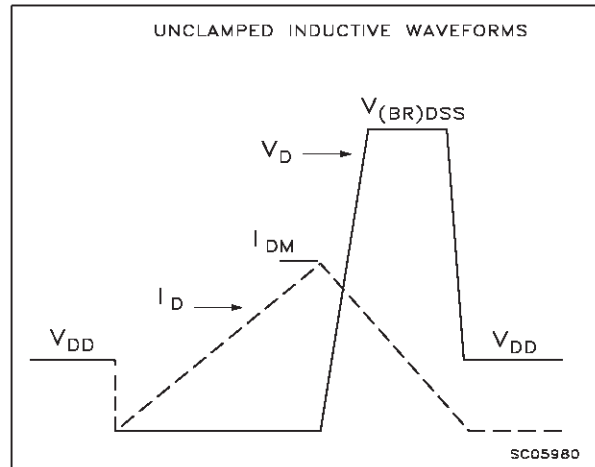
Maximum Avalanche Energy vs Temperature



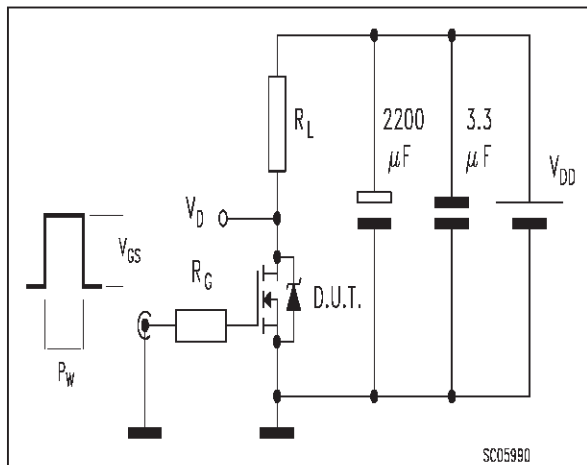
**Fig. 1: Unclamped Inductive Load Test Circuit**



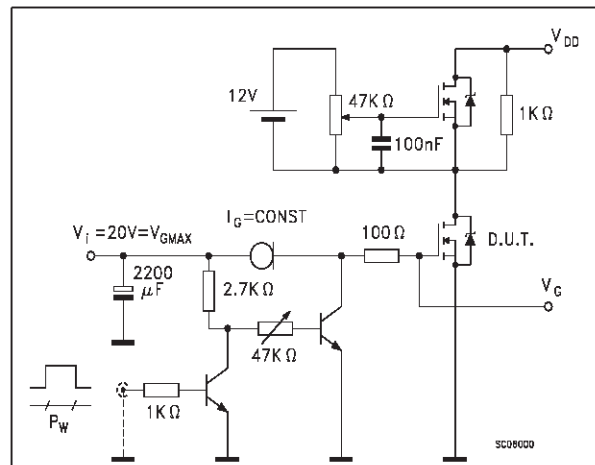
**Fig. 2: Unclamped Inductive Waveform**



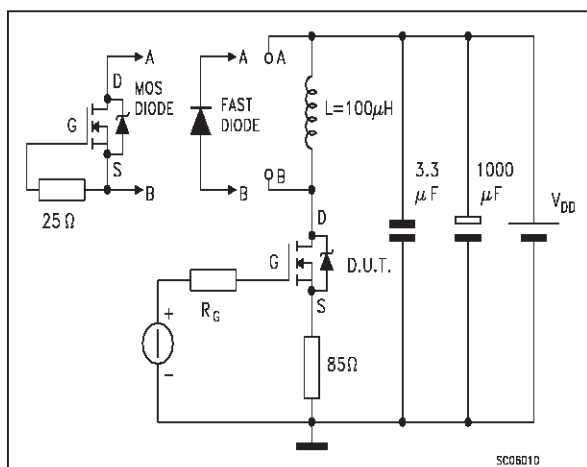
**Fig. 3: Switching Times Test Circuit For Resistive Load**



**Fig. 4: Gate Charge test Circuit**

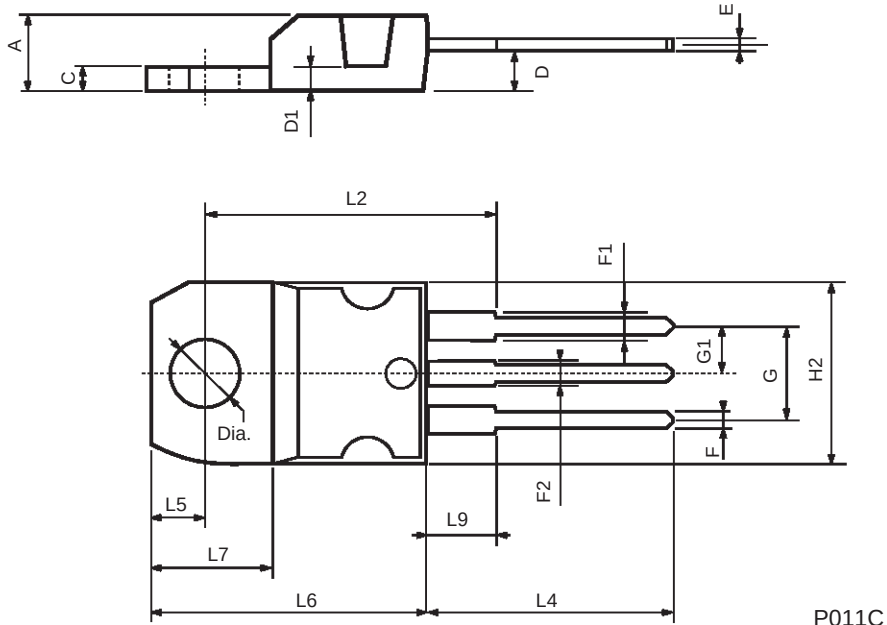


**Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times**



TO-220 MECHANICAL DATA

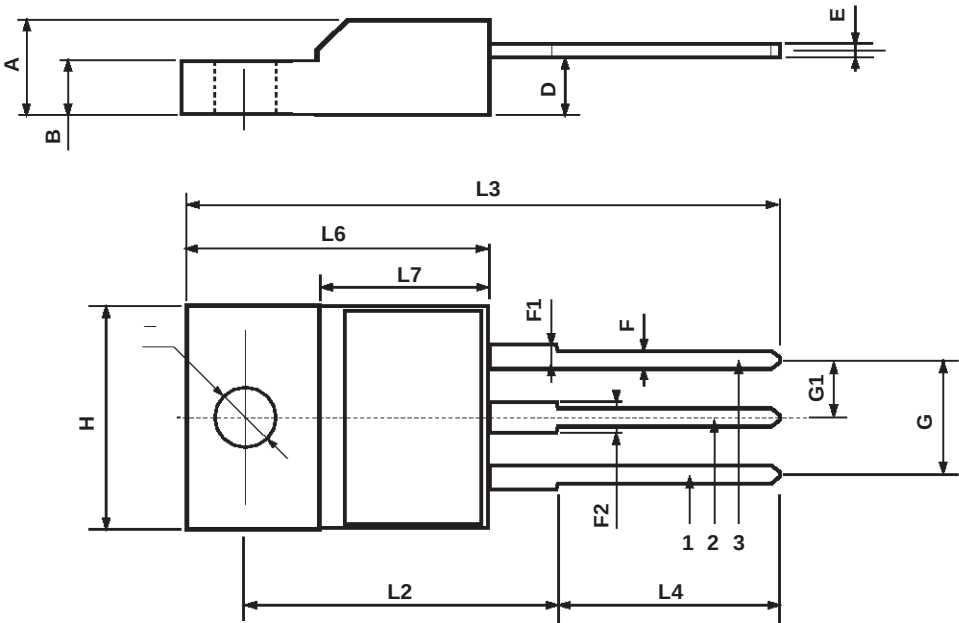
| DIM. | mm    |      |       | inch  |       |       |
|------|-------|------|-------|-------|-------|-------|
|      | MIN.  | TYP. | MAX.  | MIN.  | TYP.  | MAX.  |
| A    | 4.40  |      | 4.60  | 0.173 |       | 0.181 |
| C    | 1.23  |      | 1.32  | 0.048 |       | 0.051 |
| D    | 2.40  |      | 2.72  | 0.094 |       | 0.107 |
| D1   |       | 1.27 |       |       | 0.050 |       |
| E    | 0.49  |      | 0.70  | 0.019 |       | 0.027 |
| F    | 0.61  |      | 0.88  | 0.024 |       | 0.034 |
| F1   | 1.14  |      | 1.70  | 0.044 |       | 0.067 |
| F2   | 1.14  |      | 1.70  | 0.044 |       | 0.067 |
| G    | 4.95  |      | 5.15  | 0.194 |       | 0.203 |
| G1   | 2.4   |      | 2.7   | 0.094 |       | 0.106 |
| H2   | 10.0  |      | 10.40 | 0.393 |       | 0.409 |
| L2   |       | 16.4 |       |       | 0.645 |       |
| L4   | 13.0  |      | 14.0  | 0.511 |       | 0.551 |
| L5   | 2.65  |      | 2.95  | 0.104 |       | 0.116 |
| L6   | 15.25 |      | 15.75 | 0.600 |       | 0.620 |
| L7   | 6.2   |      | 6.6   | 0.244 |       | 0.260 |
| L9   | 3.5   |      | 3.93  | 0.137 |       | 0.154 |
| DIA. | 3.75  |      | 3.85  | 0.147 |       | 0.151 |





TO-220FP MECHANICAL DATA

| DIM. | mm   |      |      | inch  |       |       |
|------|------|------|------|-------|-------|-------|
|      | MIN. | TYP. | MAX. | MIN.  | TYP.  | MAX.  |
| A    | 4.4  |      | 4.6  | 0.173 |       | 0.181 |
| B    | 2.5  |      | 2.7  | 0.098 |       | 0.106 |
| D    | 2.5  |      | 2.75 | 0.098 |       | 0.108 |
| E    | 0.45 |      | 0.7  | 0.017 |       | 0.027 |
| F    | 0.75 |      | 1    | 0.030 |       | 0.039 |
| F1   | 1.15 |      | 1.7  | 0.045 |       | 0.067 |
| F2   | 1.15 |      | 1.7  | 0.045 |       | 0.067 |
| G    | 4.95 |      | 5.2  | 0.195 |       | 0.204 |
| G1   | 2.4  |      | 2.7  | 0.094 |       | 0.106 |
| H    | 10   |      | 10.4 | 0.393 |       | 0.409 |
| L2   |      | 16   |      |       | 0.630 |       |
| L3   | 28.6 |      | 30.6 | 1.126 |       | 1.204 |
| L4   | 9.8  |      | 10.6 | 0.385 |       | 0.417 |
| L6   | 15.9 |      | 16.4 | 0.626 |       | 0.645 |
| L7   | 9    |      | 9.3  | 0.354 |       | 0.366 |
| Ø    | 3    |      | 3.2  | 0.118 |       | 0.126 |



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